# 27 - Line SCSI Terminator With Split Reverse Disconnect

#### **FEATURES**

- Complies with SCSI, SCSI-2, SCSI-3, SPI and FAST-20 (Ultra) Standards
- 2.5pF Channel Capacitance During Disconnect
- 100μA Supply Current in Disconnect Mode
- 4V To 7V Operation
- 110Ω Termination
- Completely Meets SCSI Hot Plugging
- –900mA Sourcing Current for Termination
- +500mA Sinking Current for Active Negation
- Logic Command Disconnects all Termination Lines
- Split Reverse Controls Lines 1 to 9 and 10 to 27 Separately
- Trimmed Impedance to 5%
- Current Limit and Thermal Shutdown Protection

#### DESCRIPTION

UCC5621 provides 27 lines of active termination for a SCSI (Small Computer Systems Interface) parallel bus. The SCSI standard recommends active termination at both ends of the cable.

The UCC5621 is ideal for high performance 5V SCSI systems. During disconnect the supply current is typically only  $100\mu A$ , which makes the IC attractive for lower powered systems.

The UCC5621 features a split reverse disconnect allowing the user to control termination lines 10 to 27 with disconnect one, DISCNCT1, and control termination lines 1 to 9 with disconnect two, DISCNCT2.

The UCC5621 is designed with a low channel capacitance of 2.5pF, which eliminates effects on signal integrity from disconnected terminators at interim points on the bus.

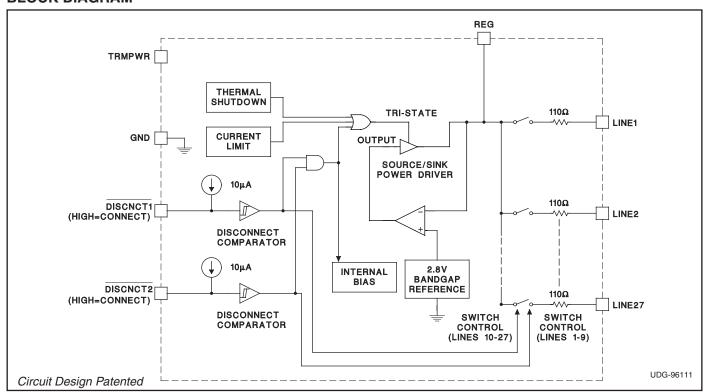
The power amplifier output stage allows the UCC5621 to source full termination current and sink active negation current when all termination lines are actively negated.

The UCC5621, as with all Unitrode terminators, is completely hot pluggable and appears as high impedance at the teminating channels with VTRMPWR = 0V or open.

Internal circuit trimming is utilized, first to trim the  $110\Omega$  impedance, and then most importantly, to trim the output current as close to the maximum SCSI-3 specification as possible, which maximizes noise margin in FAST-20 SCSI operation.

(continued)

# **BLOCK DIAGRAM**



# **DESCRIPTION** (cont.)

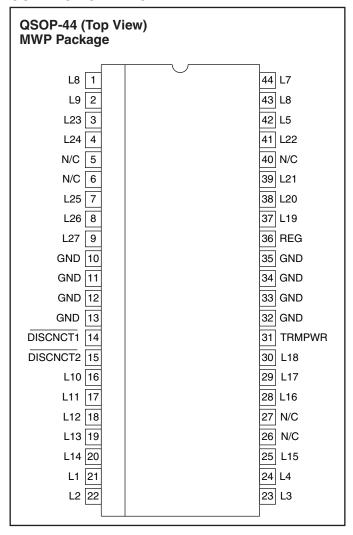
Other features include thermal shutdown and current limit. This device is offered in low thermal resistance versions of the industry standard 44 pin wide body QSOP (MWP). Consult QSOP-44 Packaging Diagrams for exact dimensions.

## **ABSOLUTE MAXIMUM RATINGS**

TRMPWR Voltage	+7V
Signal Line Voltage	+7V
Regulator Output Current	1.5A
Storage Temperature65°C to +15	50°C
Junction Temperature55°C to +15	50°C
Lead Temperature (Soldering, 10 Sec.)+30	O0°C

Currents are positive into, negative out of the specified terminal. Consult Packaging Section of Databook for thermal limitations and considerations of packages.

### **CONNECTION DIAGRAM**



# **ELECTRICAL CHARACTERISTICS** Unless otherwise stated, these specifications apply for T<sub>A</sub> = 0°C to 70°C, TRMPWR = 4.75V, DISCNCT1 = DSCNCT2 = 4.75V, T<sub>A</sub> = T<sub>A</sub>

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
<b>Supply Current Section</b>					
TRMPWR Supply Current	All Termination Lines = Open		1	2	mA
	All Termination Lines = 0.2V		630	650	mA
Power Down Mode	DISCNCT1 = DSCNCT2 = 0V		100	200	μΑ
Output Section (Termination Li	nes)				
Termination Impedance	(Note 3)	104.5	110	115.5	Ω
Output High Voltage	(Note 1)	2.6	2.8	3.0	V
Max Output Current	$V_{LINE} = 0.2V, T_J = 25^{\circ}C$	-22.1	-23.3	-24	mA
	$V_{LINE} = 0.2V$	-20.7	-23.3	-24	mA
	$V_{LINE} = 0.2V$ , TRMPWR = 4V, $T_J = 25$ °C (Note 1)	-21	-23	-24	mA
	V <sub>LINE</sub> = 0.2V, TRMPWR = 4V (Note 1)	-20	-23	-24	mA
	$V_{LINE} = 0.5V$			-22.4	mA
Output Leakage	$\overline{\text{DISCNCT1}} = \overline{\text{DISCNCT2}} = 0V$ , TRMPWR = 0V to 5.25V		10	400	nA
Output Capacitance	DISCNCT1 = DISCNCT2 = 0V (Note 2)		2.5	4	pF

**ELECTRICAL CHARACTERISTICS** Unless otherwise stated, these specifications apply for  $T_A = 0$ °C to 70°C,

TRMPWR = 4.75V, DISCNCT1 = DSCNCT2 = 4.75V,  $T_A = T_J$ .

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS				
Regulator Section									
Regulator Output Voltage		2.6	2.8	3.0	V				
Drop Out Voltage	All Termination Lines = 0.2V		0.4	0.8	V				
Short Circuit Current	V <sub>REG</sub> = 0V	-650	-900	-1300	mA				
Sinking Current Capability	V <sub>REG</sub> = 3.5V	300	500	900	mA				
Thermal Shutdown			170		°C				
Thermal Shutdown Hysteresis			10		°C				
Disconnect Section									
Disconnect Threshold DISCNCT1	Controls Lines 10 to 27	0.8	1.5	2.0	V				
Input Current DISCNCT1	DISCNCT1 = 0V		-10	-30	μΑ				
Disconnect Threshold DISCNCT2	Controls Lines 1 to 9	0.8	1.5	2	V				
Input Current DISCNCT2	DISCNCT2 = 0V		-10	-30	μΑ				

Note 1: Measuring each termination line while other 26 are low (0.2V).

Note 2: Ensured by design. Not 100% tested in production.

Note 3: Tested by measuring  $I_{OUT}$  with  $V_{OUT} = 0.2V$  and  $V_{OUT}$  with no load, then calculate:

$$Z = \frac{V_{OUT} \ N.L. - 0.2V}{I_{OUT} \ at \ 0.2V}$$

#### **PIN DESCRIPTIONS**

DISCNCT1: Disconnect one controls termination lines L10 – L27. Taking this pin low causes termination lines L10 – L27 to become high impedence, taking this pin high or leaving it open allows the channels to provide normal termination.

**DISCNCT2**: Disconnect two controls termination lines L1 – L9. Taking this pin low causes termination lines L1 – L9 to become high impedence. Taking this pin high or leaving it open allows the channels to provide normal terminiation. Taking both disconnect pins low will put the chip in to sleep mode where it will be in low-power mode.

**GND:** Ground reference for the IC.

**L1 - L27:**  $110\Omega$  termination channels.

**REG:** Output of the internal 2.7V regulator.

TRMPWR: Power for the IC.

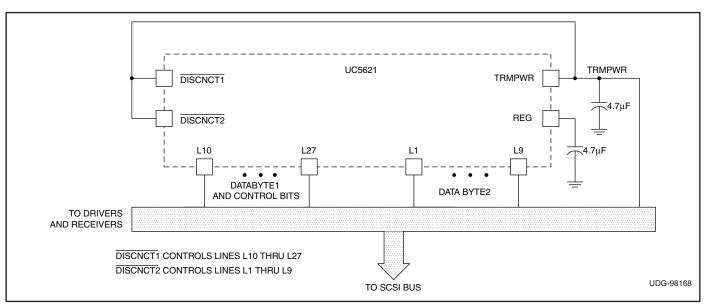


Figure 1. Typical Wide SCSI Bus Configuration Using the UCC5621

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